


Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes evenly
- Clamshell lid

Materials:

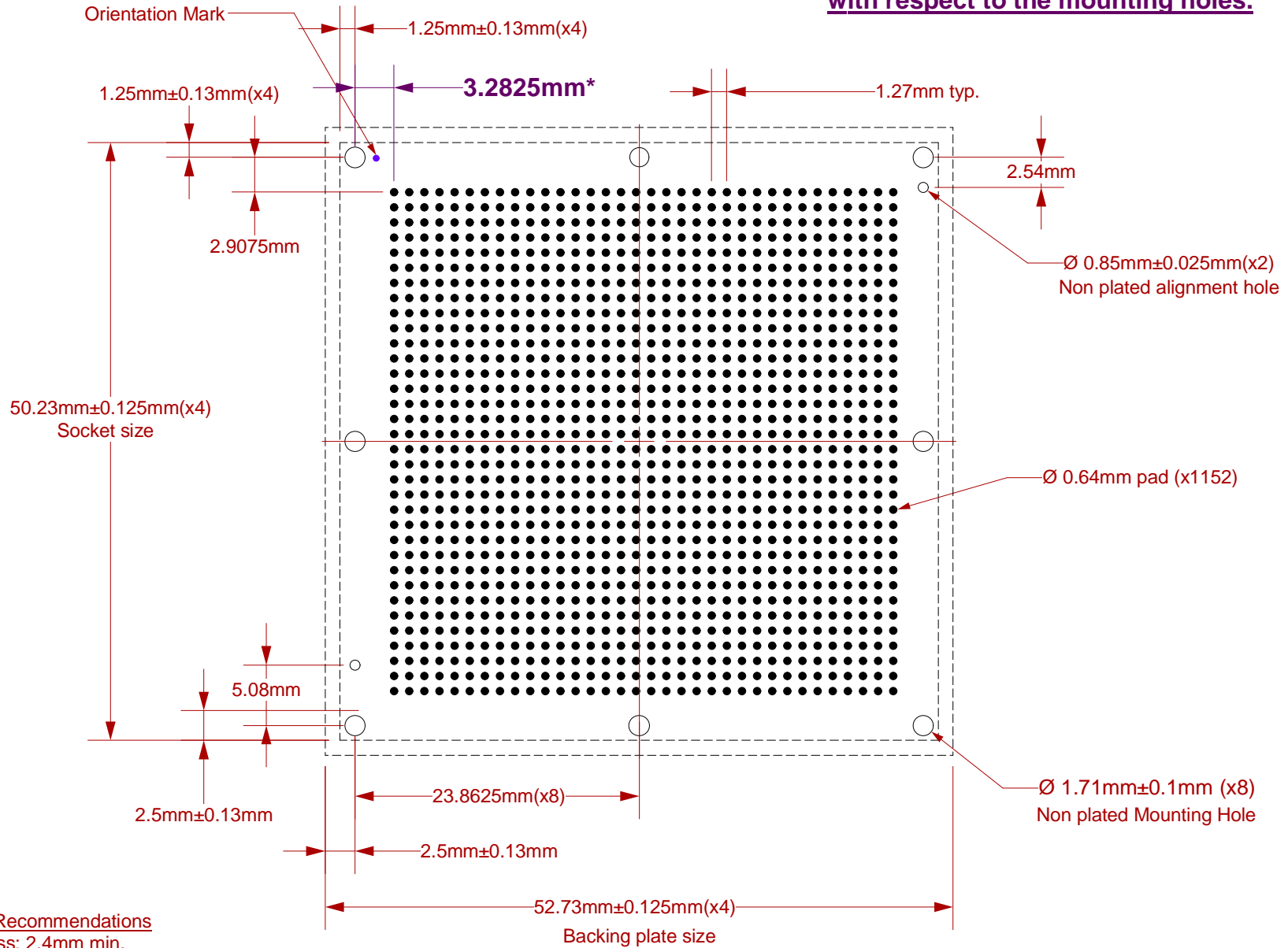
- 1 Clam Shell Lid: Black anodized Aluminum. Height = 20 mm.
- 2 Socket Base: Black anodized Aluminum. Height = 6 mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 12 mm.
- 4 Compression Screw: Clear anodized Aluminum. Height = 27 mm, Fluted Knob
- 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- 6 Elastomer Guide: Non-clad FR4. Thickness = 0.725mm.
- 7 Socket Base Screw: Socket Head Cap Screw, Black Oxide, 0-80 Thread, 5/8" long.
- 8 Backing Plate: Black anodized Aluminum
- 9 Insulation Plate: FR4/G10
- 10 Ball Guide: Kapton polyimide.
- 11 Latch: Black anodized 7075 Aluminum.

	CG-BGA-4013 Drawing	Status: Released	Scale: -	Rev: A
	© 2010 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: E Smolentseva	Date: 7/14/10	
		File: CG-BGA-4013 Dwg	Modified:	

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View

***Note: BGA pattern is shifted to the right by 0.375mm with respect to the mounting holes.**




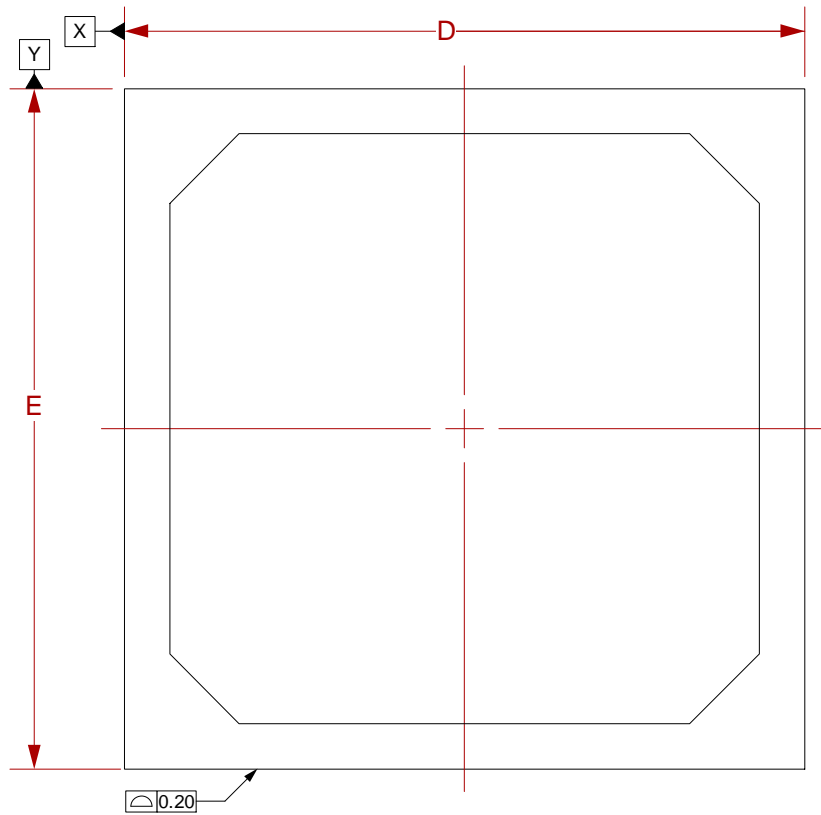
Target PCB Recommendations

Total thickness: 2.4mm min.
 Plating: Gold or Solder finish
 PCB Pad height: Same or higher than solder mask

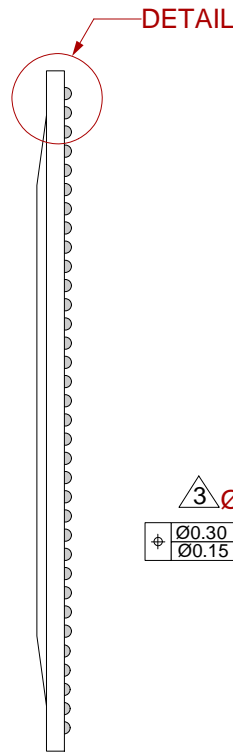
NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

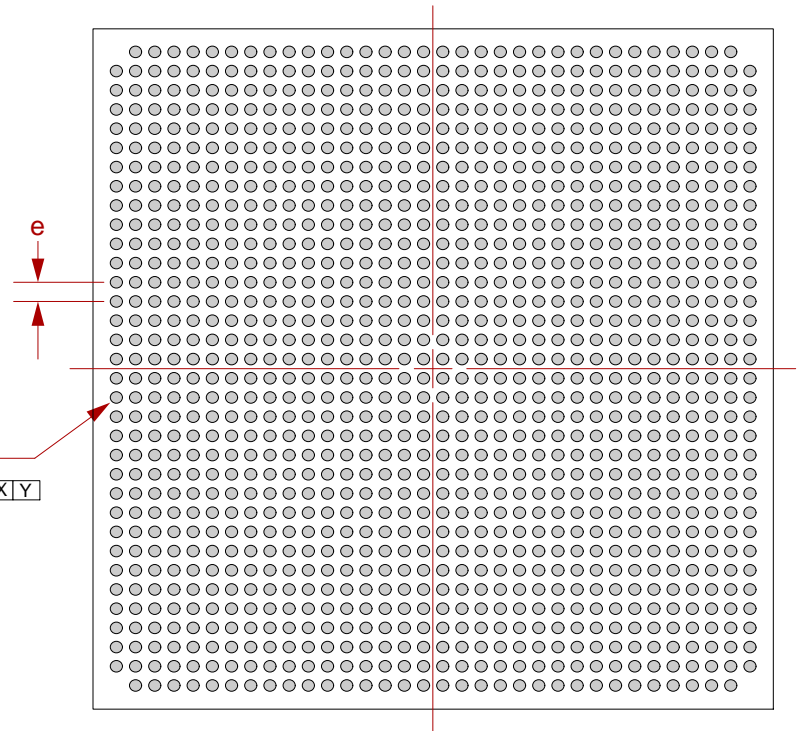
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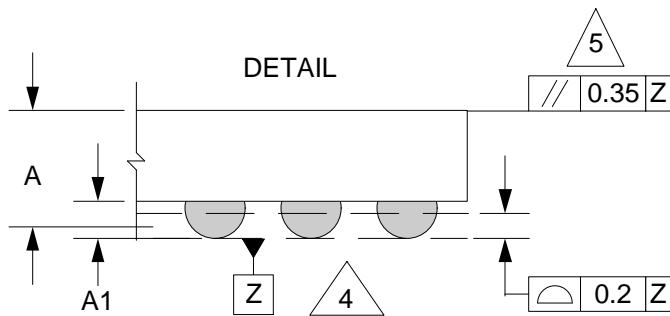
TOP VIEW



SIDE VIEW




BOTTOM VIEW



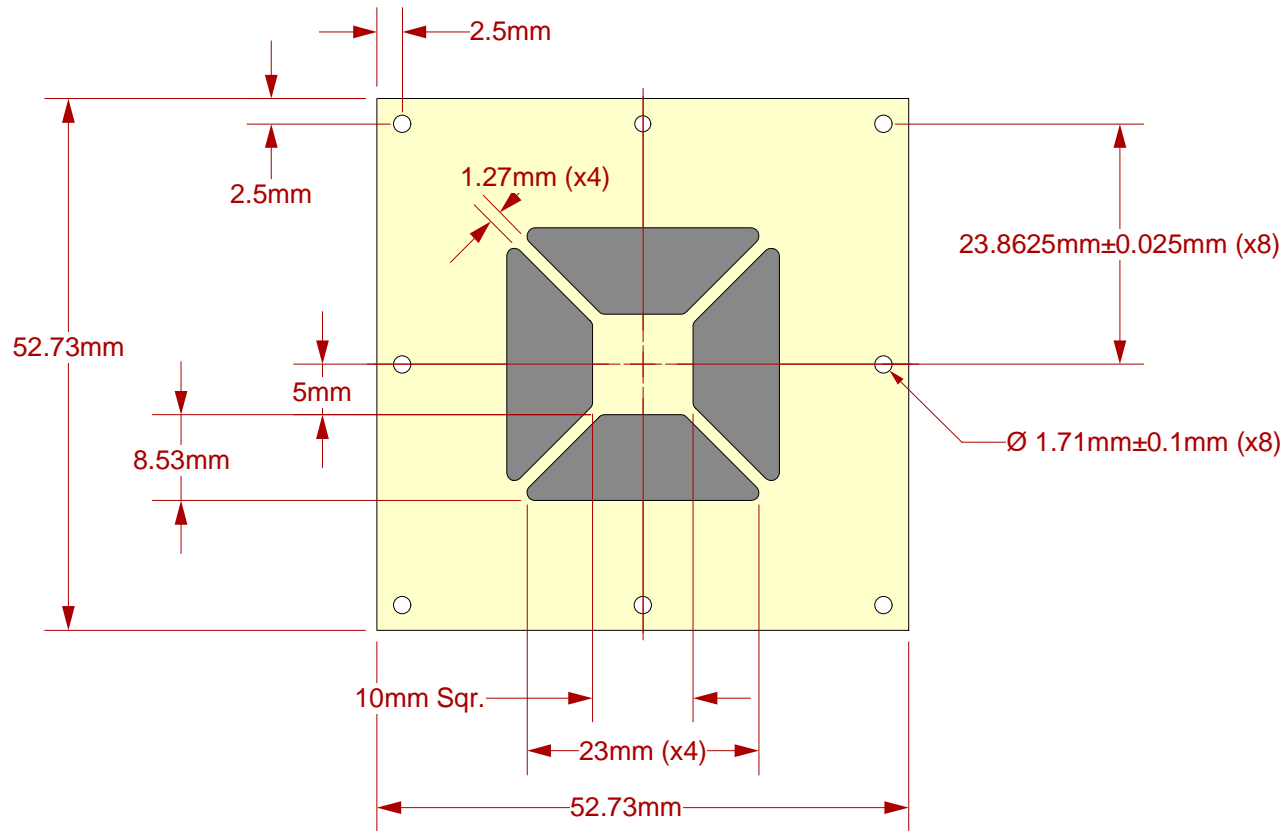
1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
 - 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
 - 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.51
A1	0.5	0.7
b		0.90
D	45 BSC	
E	45 BSC	
e	1.27 BSC	

Array: 34 x 34

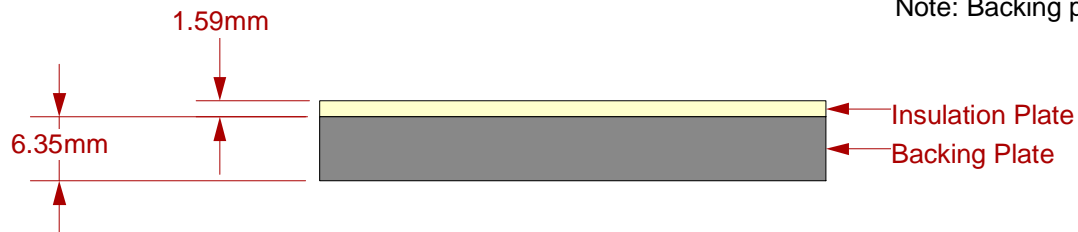
 <p>© 2010 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	CG-BGA-4013 Drawing	Status: Released	Scale: -	Rev: A
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Top View




Note: Backing plate holes are tapped to accept 0-80 screws.

Side View



Description: Backing Plate with Insulation Plate

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			File: CG-BGA-4013 Dwg	
			Modified:	

All dimensions are in mm.
 All tolerances are +/- 0.125mm.
 (Unless stated otherwise)